



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



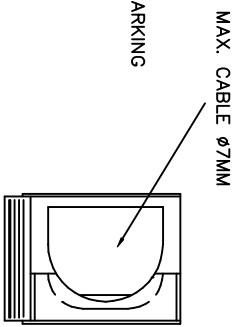
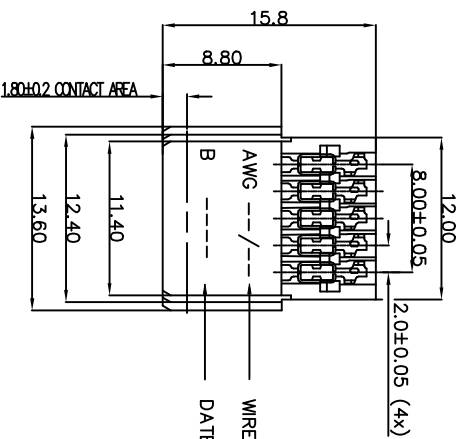
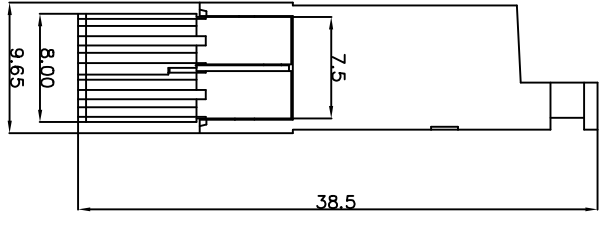
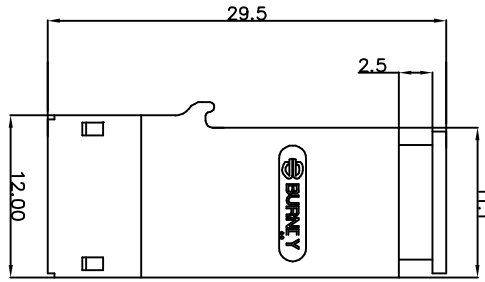
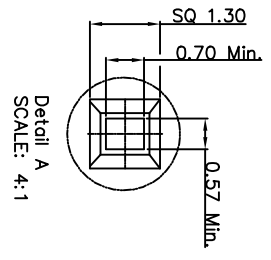
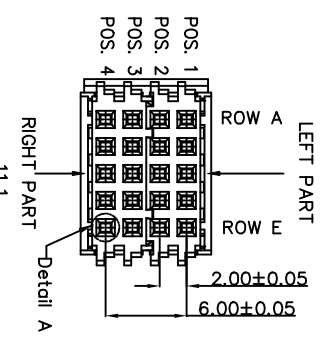
Contact us

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Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





NOTE:
PERFORMANCE CHARACTERISTICS:

VOLTAGE RATING : 250 VAC
 CURRENT RATING : 1.0 A AT 70°C
 INSULATION RESISTANCE¹ 10 MΩ MIN. AFTER TEST
 DIELECTRIC WITHSTANDING VOLTAGE: 1000V
 CONTACT RESISTANCE: 20 mΩ Max. AFTER TEST
 OPERATING T : -55°C TO +125°C
 INSERTION FORCE: 0.75N Max. PER CONTACT
 WITHDRAWAL FORCE: 0.15N Min. PER CONTACT

MATERIALS:

TERMINAL BLOCK : GLASS REINFORCED THERMOPLASTIC UL94-V0.
 COVER : PDL YAMIDE-NYLON.
 CONTACTS : PHOSPHOR BRONZE.
 PLATING : Z1 : 0.40 μ Au MIN. OVER Ni IN CONTACT AREA;
 N9 : 0.75 μ Au MIN. OVER Ni IN CONTACT AREA;
 PURE Sn DN IDC-TERMINAL.
 EB : 2.00 μ Au MIN. OVER Ni IN CONTACT AREA;
 PURE Sn DN IDC-TERMINAL.

WIRE CHARACTERISTICS:

26/28/30AWG: INSULATION DIAMETER 1.20MM MAX.
 24AWG SPECIAL: INSULATION DIAMETER 0.9 MM MAX.

PART NUMBERS:

HM2C01D0C010--LF CONNECTOR FOR WIRE SIZE AWG 28, AWG 30.
 HM2C01D2C010--LF CONNECTOR FOR WIRE SIZE AWG 24, AWG 26.
 AWG24 SPECIAL SEE WIRE CHARACTERISTICS

MARKING:

| PARTNUMBER | WIRE SIZE MARKING |
|------------------|-------------------|
| HM2C01D0C010--LF | AWG28/30 |
| HM2C01D2C010--LF | AWG24/26 |

- THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
- THE PRODUCT IS NOT INTENDED TO BE EXPOSED TO A MANUFACTURING SOLDER PROCESS

| mat'l. code | surface | tolerance | projection | product family |
|-------------|------------|-----------------|---------------------------------------|--|
| ltr | ISO 1302 | ISO 406/ISO 110 | specified | Millipacs HPL560 |
| A | ecn no dr | date | tolerances unless otherwise specified | |
| B | 0695-0491 | 01 22-11-05 | 0.0 ± 0.2 | 4X5 Pos, HM2C01D-C010-LF |
| C | EL-N-26087 | U 2017/02/13 | 0.00 ± 0.1 | NON-SHIELDED CABLE CONNECTOR WITH H000 |
| | dr | Laurence Zang | 0±1 | scale 4:1 |
| | enq | Laurence Zang | 2017/02/13 | Amphenol FCI |
| | chr | Nick Zhang | 2017/02/13 | BSD201630005 |
| | qppd | Tim Yao | 2017/02/13 | Product Customer Drawing |
| sheet index | revision | c | | type |
| | sheet | 1 | | sheet of 1 size |
| | | | | A4 |